

MOSFETs Silicon N-channel MOS (U-MOSIX-H)

XPH1R104PS

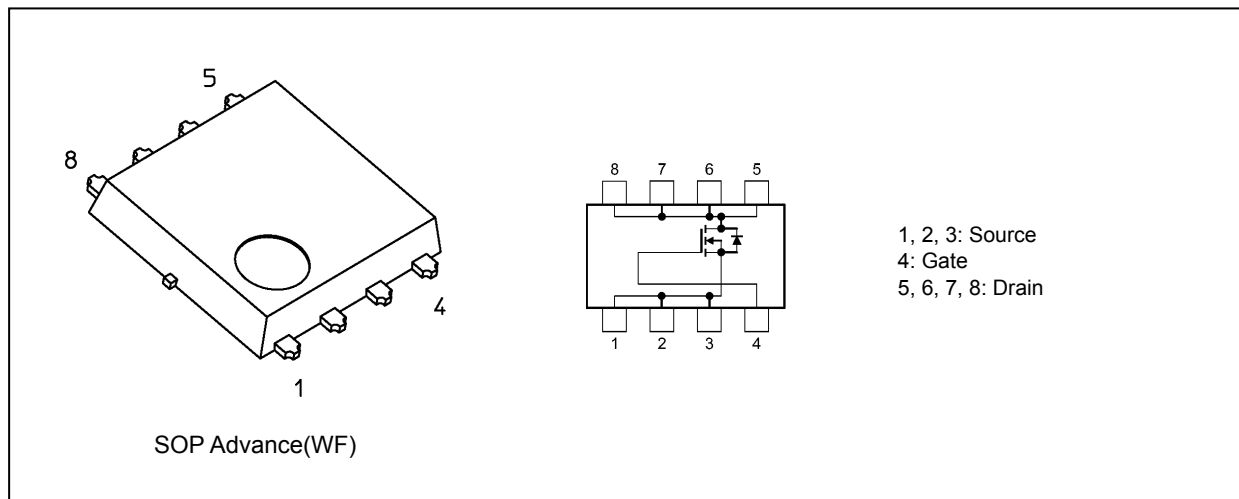
1. Applications

- Automotive
- Motor Drivers
- Switching Voltage Regulators

2. Features

- (1) AEC-Q101 qualified
- (2) Small, thin package
- (3) Low drain-source on-resistance: $R_{DS(ON)} = 0.95 \text{ m}\Omega$ (typ.) ($V_{GS} = 10 \text{ V}$)
- (4) Low leakage current: $I_{DSS} = 10 \text{ }\mu\text{A}$ (max) ($V_{DS} = 40 \text{ V}$)
- (5) Enhancement mode: $V_{th} = 2.0 \text{ to } 3.0 \text{ V}$ ($V_{DS} = 10 \text{ V}$, $I_D = 0.5 \text{ mA}$)

3. Packaging and Internal Circuit



Start of commercial production

2021-10

4. Absolute Maximum Ratings (Note) ($T_a = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

Characteristics	Symbol	Rating	Unit
Drain-source voltage	V_{DS}	40	V
Gate-source voltage	V_{GS}	± 20	
Drain current (DC) (Note 1)	I_D	120	A
Drain current (pulsed) (Note 1)	I_{DP}	360	
Power dissipation ($T_c = 25\text{ }^{\circ}\text{C}$)	P_D	132	W
Power dissipation ($t = 10\text{ s}$) (Note 2)		3.0	
Power dissipation ($t = 10\text{ s}$) (Note 3)		0.96	
Single-pulse avalanche energy (Note 4)	E_{AS}	140	mJ
Single-pulse avalanche current	I_{AS}	120	A
Channel temperature (Note 5)	T_{ch}	175	$^{\circ}\text{C}$
Storage temperature (Note 5)	T_{stg}	-55 to 175	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

5. Thermal Characteristics

Characteristics	Symbol	Max	Unit
Channel-to-case thermal impedance ($T_c = 25\text{ }^{\circ}\text{C}$)	$Z_{th(ch-c)}$	1.13	$^{\circ}\text{C/W}$
Channel-to-ambient thermal impedance ($t = 10\text{ s}$) (Note 2)	$Z_{th(ch-a)}$	50	
Channel-to-ambient thermal impedance ($t = 10\text{ s}$) (Note 3)	$Z_{th(ch-a)}$	156	

Note 1: Ensure that the channel temperature does not exceed $175\text{ }^{\circ}\text{C}$.

Note 2: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 3: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 4: $V_{DD} = 32\text{ V}$, $T_{ch} = 25\text{ }^{\circ}\text{C}$ (initial), $L = 7.47\text{ }\mu\text{H}$, $R_G = 25\text{ }\Omega$, $I_{AS} = 120\text{ A}$

Note 5: The definitions of the absolute maximum channel and storage temperatures are qualified per AEC-Q101.



Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a)

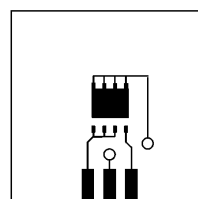


Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

6. Electrical Characteristics

6.1. Static Characteristics ($T_a = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current	I_{GSS}	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$	—	—	± 1	μA
Drain cut-off current	I_{DSS}	$V_{DS} = 40\text{ V}, V_{GS} = 0\text{ V}$	—	—	10	
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = 10\text{ mA}, V_{GS} = 0\text{ V}$	40	—	—	V
	$V_{(BR)DSX}$	$I_D = 10\text{ mA}, V_{GS} = -20\text{ V}$	20	—	—	
Gate threshold voltage	V_{th}	$V_{DS} = 10\text{ V}, I_D = 0.5\text{ mA}$	2.0	—	3.0	
Drain-source on-resistance	$R_{DS(ON)}$	$V_{GS} = 6\text{ V}, I_D = 60\text{ A}$	—	1.30	1.96	$\text{m}\Omega$
		$V_{GS} = 10\text{ V}, I_D = 60\text{ A}$	—	0.95	1.14	

6.2. Dynamic Characteristics ($T_a = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Input capacitance	C_{iss}	$V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V}, f = 300\text{ kHz}$	—	4560	—	pF
Reverse transfer capacitance	C_{rss}		—	320	—	
Output capacitance	C_{oss}		—	2940	—	
Gate resistance	r_g		—	2.9	—	Ω
Switching time (rise time)	t_r	See Fig. 6.2.1	—	8	—	ns
Switching time (turn-on time)	t_{on}		—	22	—	
Switching time (fall time)	t_f		—	23	—	
Switching time (turn-off time)	t_{off}		—	71	—	

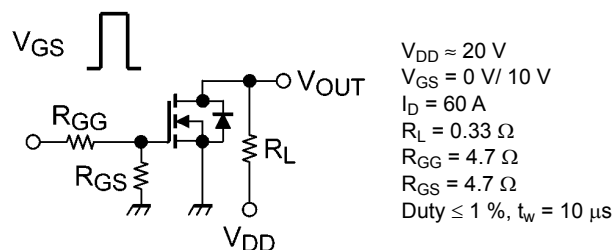


Fig. 6.2.1 Switching Time Test Circuit

6.3. Gate Charge Characteristics ($T_a = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Q_g	$V_{DD} \approx 32\text{ V}, V_{GS} = 10\text{ V}, I_D = 120\text{ A}$	—	55	—	nC
Gate-source charge 1	Q_{gs1}		—	20	—	
Gate-drain charge	Q_{gd}		—	13	—	

6.4. Source-Drain Characteristics ($T_a = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Reverse drain current (pulsed) (Note 6)	I_{DRP}	—	—	—	360	A
Diode forward voltage	V_{DSF}	$I_{DR} = 120\text{ A}, V_{GS} = 0\text{ V}$	—	—	-1.2	V

Note 6: Ensure that the channel temperature does not exceed $175\text{ }^{\circ}\text{C}$.

7. Marking

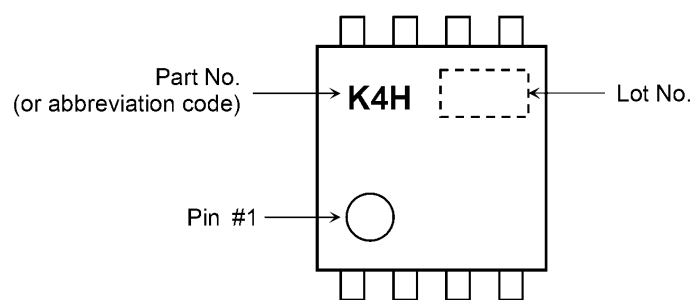
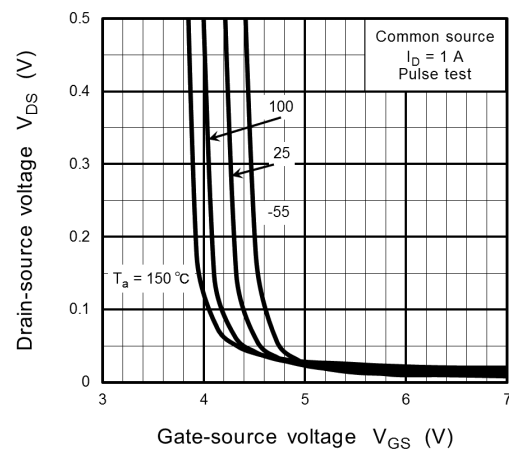
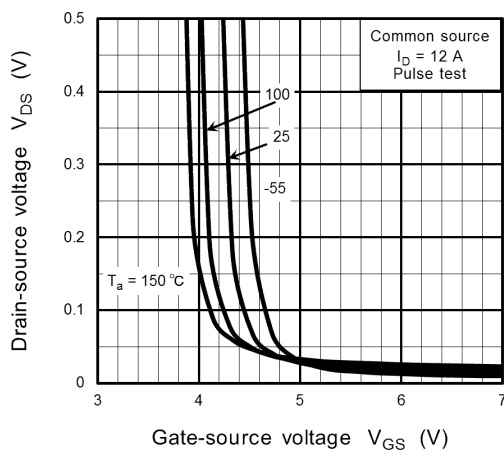
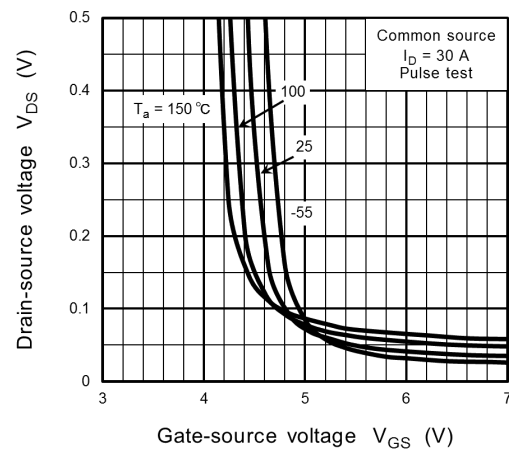
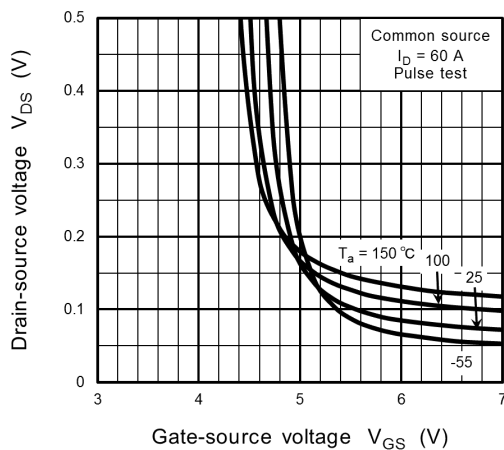
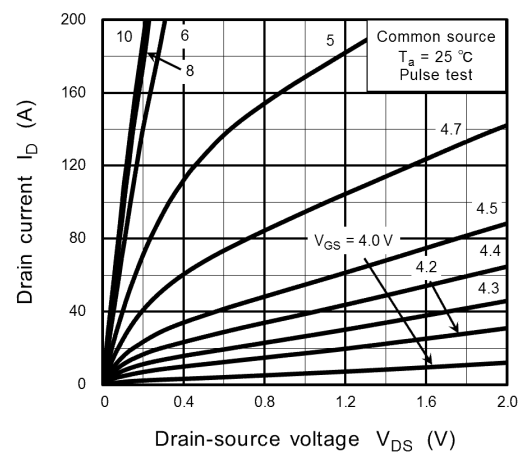
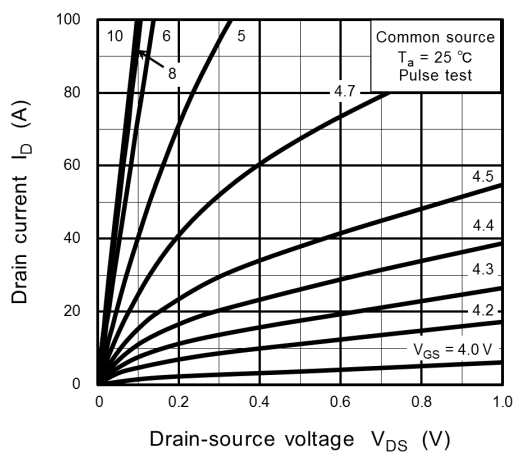


Fig. 7.1 Marking

8. Characteristics Curves (Note)



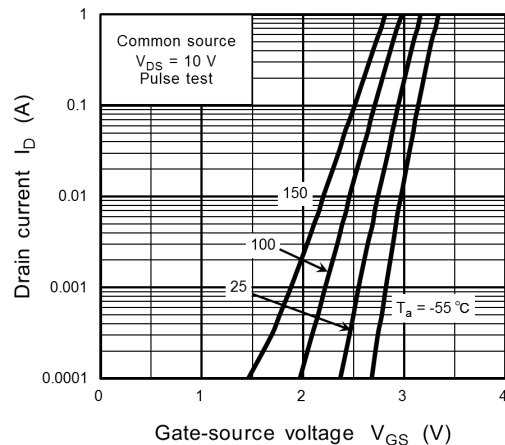


Fig. 8.7 $I_D - V_{GS}$

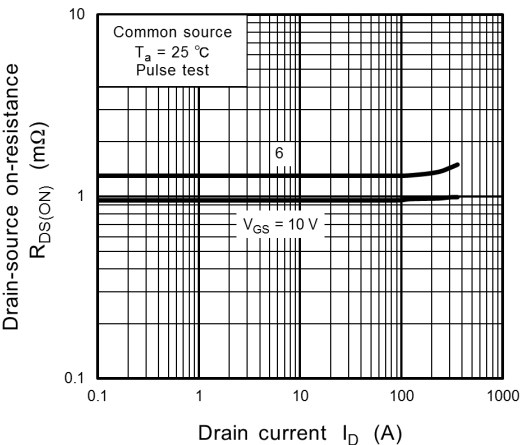


Fig. 8.8 $R_{DS(ON)} - I_D$

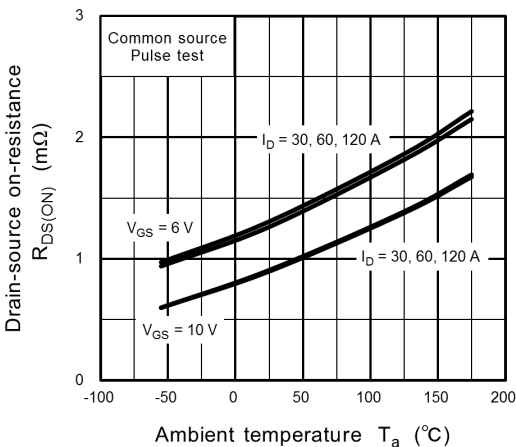


Fig. 8.9 $R_{DS(ON)} - T_a$

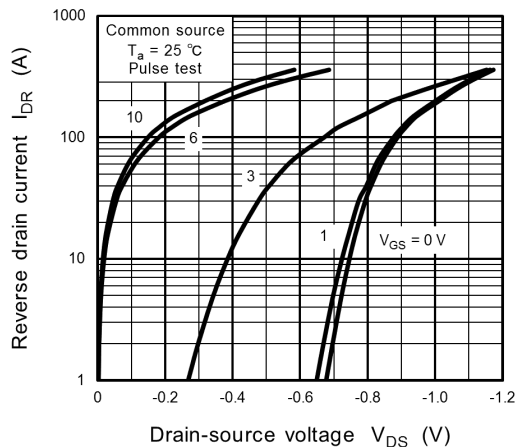


Fig. 8.10 $I_{DR} - V_{DS}$

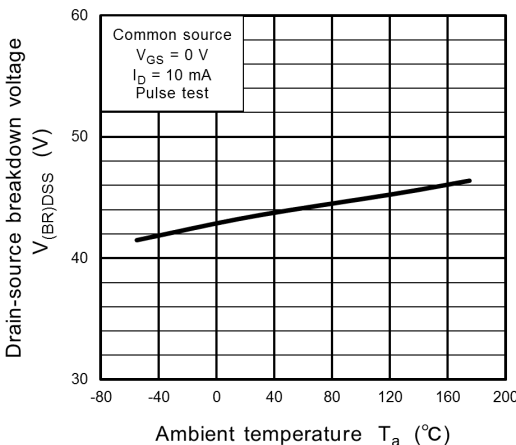


Fig. 8.11 $V_{(BR)DSS} - T_a$

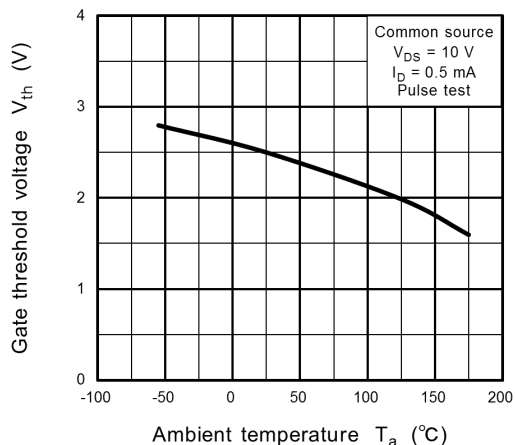


Fig. 8.12 $V_{th} - T_a$

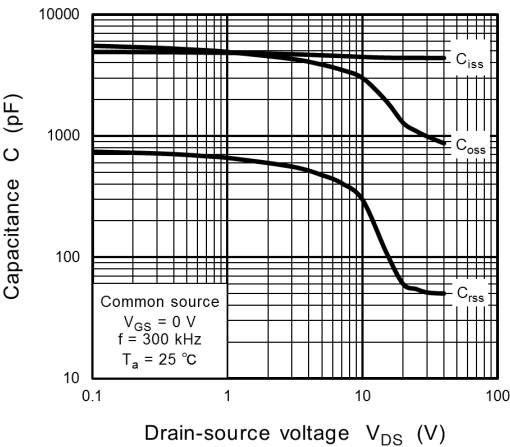


Fig. 8.13 Capacitance - V_{DS}

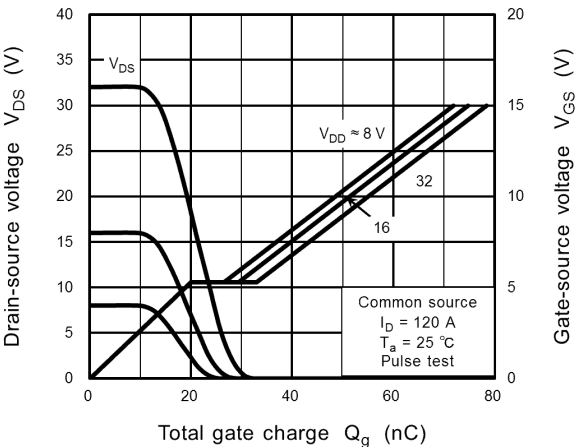


Fig. 8.14 Dynamic Input/Output Characteristics

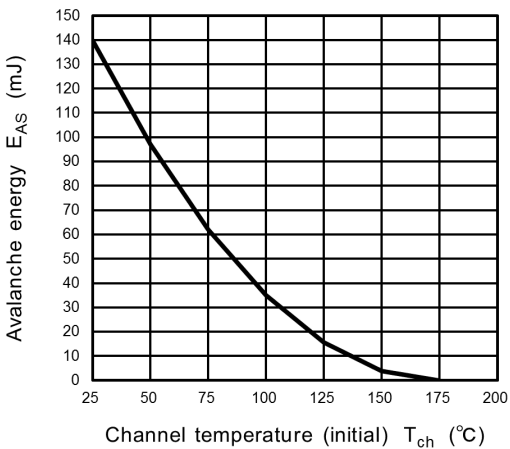


Fig. 8.15 E_{AS} - T_{ch}(Guaranteed Maximum)

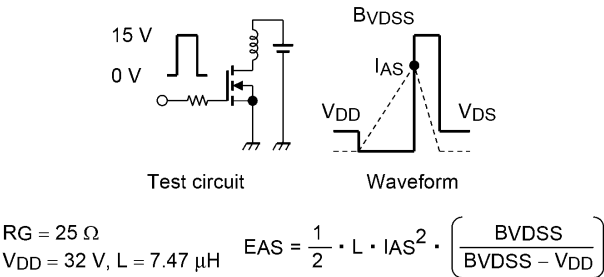


Fig. 8.16 Test Circuit/Waveform

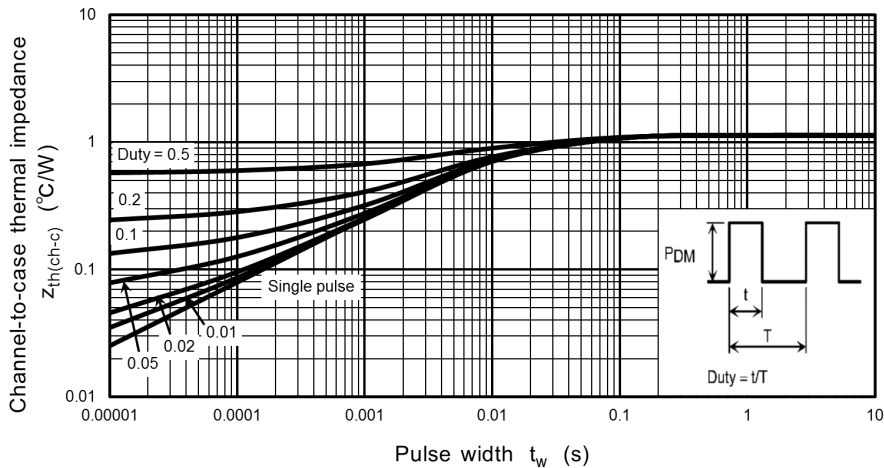


Fig. 8.17 $Z_{th(ch-c)} - t_w$
(Guaranteed Maximum)

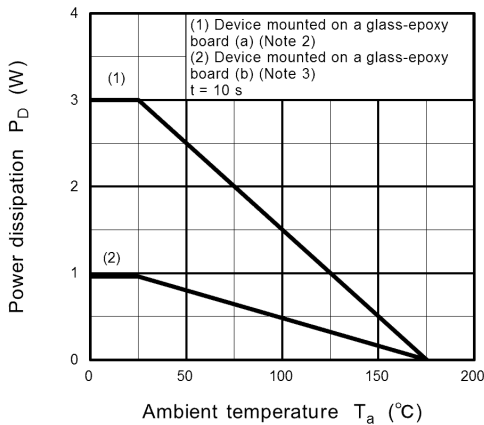


Fig. 8.18 $P_D - T_a$
(Guaranteed Maximum)

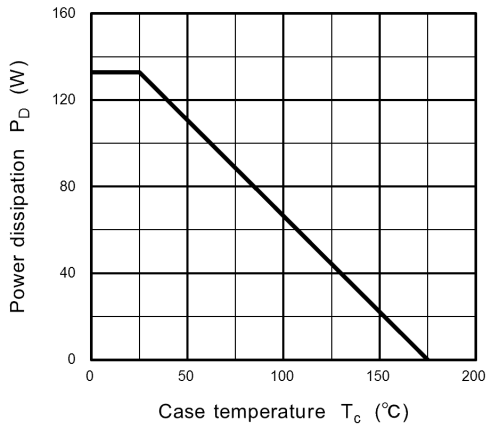


Fig. 8.19 $P_D - T_c$
(Guaranteed Maximum)

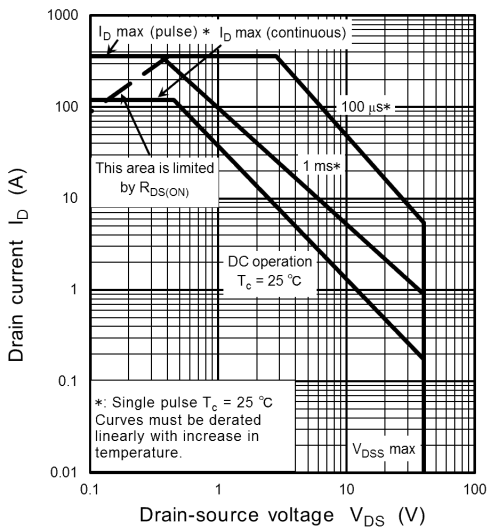
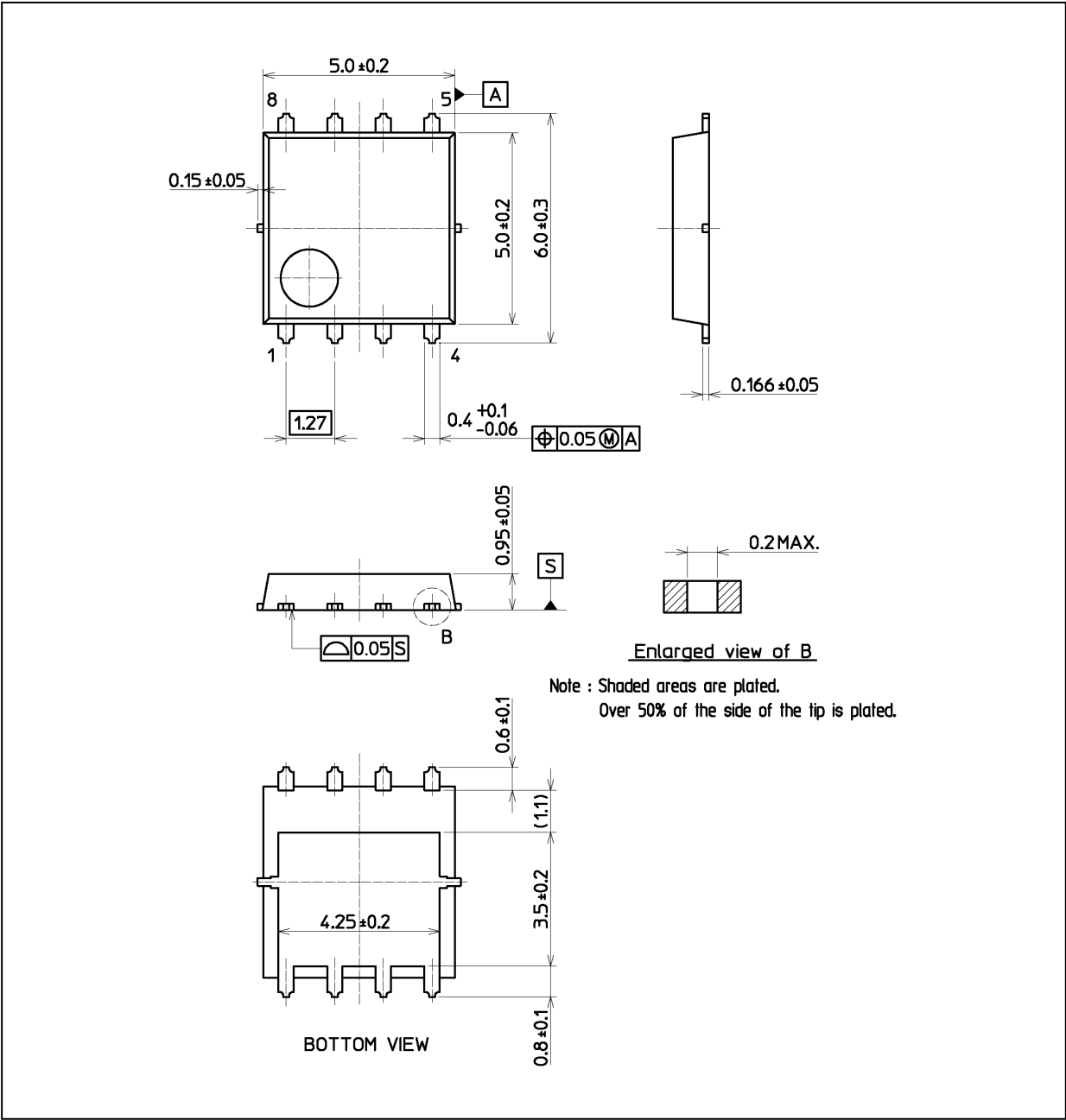


Fig. 8.20 Safe Operating Area
(Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Package Dimensions

Unit: mm



Weight: 0.080 g (typ.)

Package Name(s)
TOSHIBA: 2-5Q4A
Nickname: SOP Advance(WF)

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